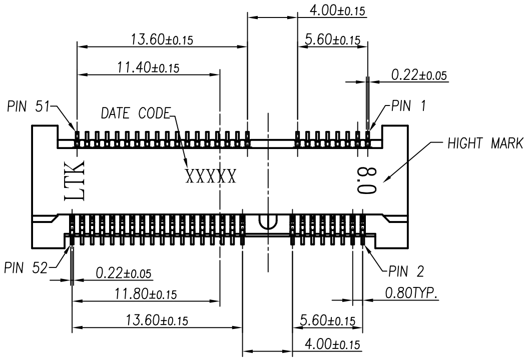
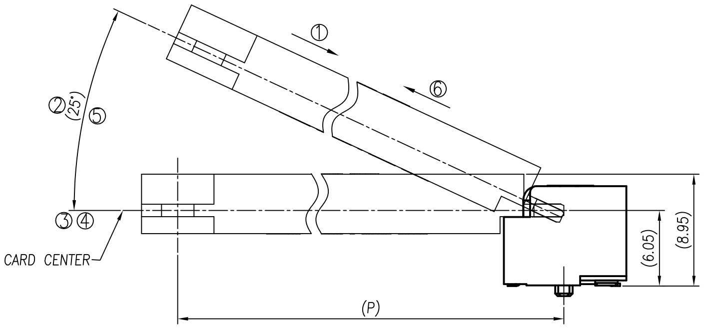
REV.	MODIFICATION	DATE	DRAW
A	INITIAL RELEASE	2012.03.07	Coco

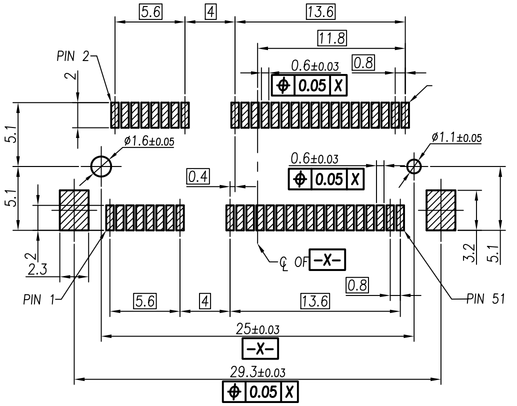
HALOGEN FREE   LEAD FREE





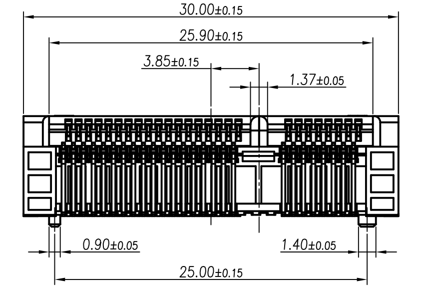
MATING: ①INSERTING(25°) ⟶ ② ROTATING ⟶ ③FIXED

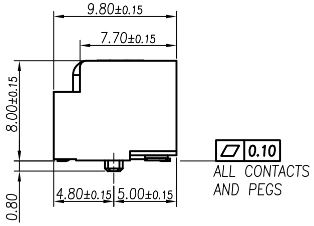
UNMATING: ④UNFIXED ⟶ ⑤ ROTATING ⟶ ⑥ WITHDRAWING



RECOMMEND PCB LAYOUT(MINIMUM THICKNESS OF THE PCB IS 0.8mm)

(OTHER TOLERANCES ARE NOT MARKED:±0.03)





NOTES:

1.MATERIAL:

HOUSING: THERMOPLASTIC , BLACK COLOR ,
FLAME RESISTANCE UL94-V0.
CONTACTS: COPPER ALLOY, THICKNESS 0.20mm.
SOLDER PEGS: COPPER ALLOY, THICKNESS 0.2mm.

2.MSL LEVEL:

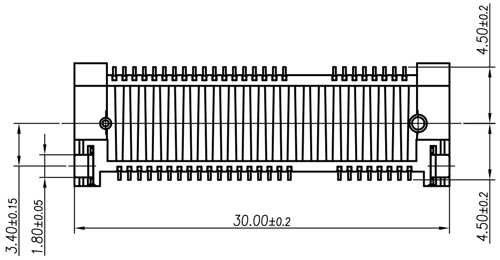
MSL(MOISTURE SENSITIVITY LEVELS)=1

3.FINISHED:

CONTACTS: GOLD PLATING ON CONTACT AREA AND
50~120u'' MATTE TIN PLATING ON SOLDER AREA.
30~120u" NICKEL UNDER-PLATING OVER ALL.
SOLDER PEGS: 50~120u" MATTE TIN PLATING OVER 50~120u"
NICKEL UNDER-PLATING OVER ALL.

4.PART NUMBER:

MPCET-S52XX-TP80
01:GOLD FLASH — TP:TAPE REEL
05:5U" MIN.
10:10U"MIN.
15:15U"MIN.
30:30U"MIN.



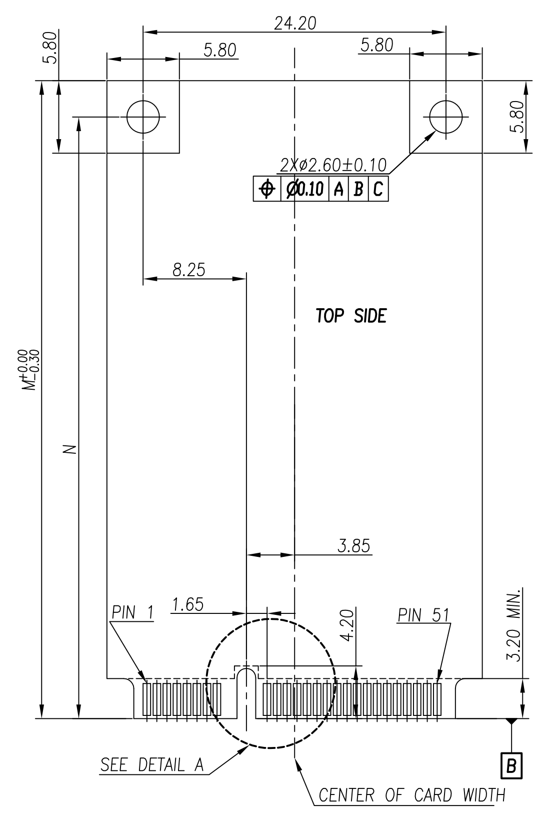
LINKTEK

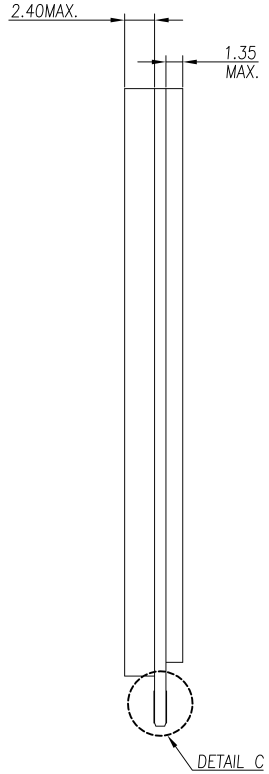
DIMENSION IN mm [Inch]		PROD. SPEC. SP-MPCXXL1	ARGOSY RESEARCH INC.	
TOLERANCE UNLESS OTHERWISE SPECIFIED		PKG. SPEC. PK-MPCET-0XX		
.X±0.35	X.°± 1°	APR. Alex 2012.03.07	TITLE: MINI PCI EXPRESS 8.0H	
.XX±0.25	.X°±	CHK. Leo 2012.03.07	FILE NO. ARG-126	DWG NO. MPCET-S52XX-TP80
.XXX±	.XX°±	DRA. Coco 2012.03.07	PROJ.	CUSTOMER DRAWING
			SIZE A4 SCALE 1:1	SHEET 1/2 REV. A C

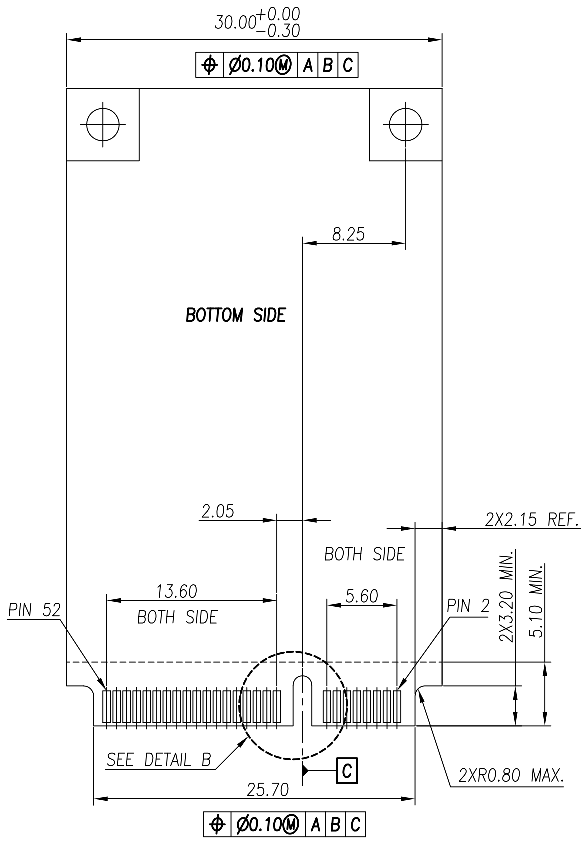
REV.	MODIFICATION	DATE	DRAW
A	INITIAL RELEASE	2012.03.07	Coco

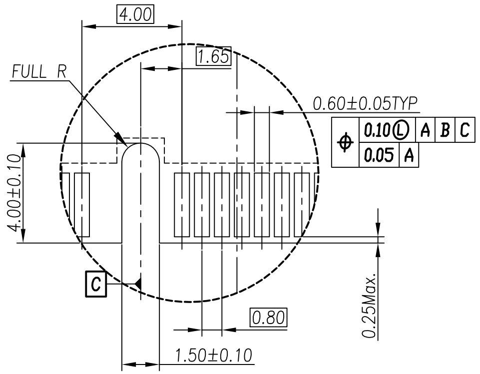
HALOGEN FREE

LEAD FREE





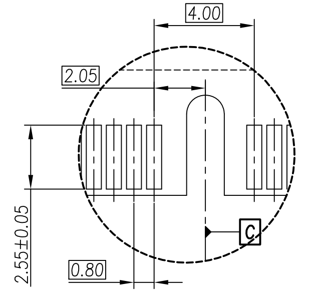




TOP SIDE

DETAIL A

SCALE 2:1

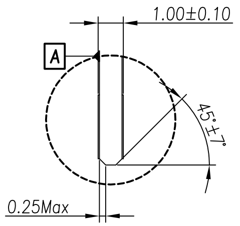


BOTTOM SIDE

DETAIL B

SCALE 2:1

LINKTEK



DETAIL C

SCALE 2:1

	M	N	P
FULL-MINI CARD	50.95	48.05	49.70
HALF-MINI CARD	26.8	23.9	25.55

DIMENSION IN mm [Inch]		PROD. SPEC. SP-MPCXXL1	ARGOSY RESEARCH INC.
TOLERANCE UNLESS OTHERWISE SPECIFIED		PKG. SPEC. PK-MPCET-0XX	
.X±0.35	X.°± 1°	APR. Alex 2012.03.07	TITLE: MINI PCI EXPRESS 8.0H
.XX±0.25	.X°±	CHK. Leo 2012.03.07	FILE NO. ARG-126 / DWG NO. MPCET-S52XX-TP80
.XXX±	.XX°±	DRA. Coco 2012.03.07	PROJ. ⊕◁ / CUSTOMER DRAWING
			SIZE A4 / SCALE 1:1 / SHEET 2/2 / REV. A / C

RD-102-15-01